

IN THE CLAIMS:

CLAIM 1(CURRENTLY AMENDED). In a CMP apparatus comprising a polishing pad having a working-surface section and a nonworking-surface section, a platen for holding said polishing pad, and means for securing said polishing pad to said platen, the improvement comprising:

said means for securing said polishing pad to said platen comprising hook-and-pile fastening means;

said hook-and-pile fastening means comprising a first portion attached to said polishing pad, and a second portion attached to said platen for mating with said first portion[.];

said hook-and-pile fastening means having a shear strength in the range of 50-250 kPa, and peel strength in the range of 0.2-0.6 N/m.

CLAIM 2(ORIGINAL). The CMP apparatus according to claim 1, wherein said polishing pad comprises a nonporous polishing pad;

said means for securing comprising first adhesive means on said nonworking-surface section of said polishing pad for attaching said first portion to said polishing pad, and second adhesive means on said platen for attaching said second portion to said platen.

CLAIM 3(ORIGINAL). The CMP apparatus according to claim 1, wherein said polishing pad comprises a porous polishing pad;

said polishing pad comprising a thermoplastic boundary layer on said nonworking-surface section of said polishing pad;

said means for securing comprising first adhesive means attached to said thermoplastic boundary layer on said nonworking- surface section of said polishing pad for attaching said first portion to said polishing pad, and second adhesive means on said platen for attaching said second portion to said platen.

CLAIM 4 (CANCELLED).

CLAIM 5(CURRENTLY AMENDED). The CMP apparatus according to claim [[4]] 5, wherein said hook-and-pile fastening means is made of CMP-non-degradable material.

CLAIM 6(ORIGINAL). The CMP apparatus according to claim 1, wherein said polishing pad comprises a porous polishing pad;

said nonworking-surface section of said polishing pad comprising a bonding layer fused thereto; said means for securing comprising first adhesive means attached to said bonding layer for attaching said first portion to said polishing pad, and second adhesive means on said platen for attaching said second portion to said platen.

CLAIM 7(ORIGINAL). The CMP apparatus according to claim 6, wherein said bonding layer is made of a water-impervious material in order to prevent CMP slurry from contacting said first and second adhesive means, having a thickness of between .025-.050 mm.

CLAIM 8(ORIGINAL). The CMP apparatus according to claim 1, wherein said first portion of said hook-and-pile fastening means comprises the hook-portion thereof having hooks, and

said second portion of said hook-and-pile fastening means comprises the pile-portion thereof having loops; said hooks of said hook-portion of said hook-and-pile fastening means being relatively stiff, and said loops of said pile-portion of said hook-and-pile fastening means being relatively soft.

CLAIM 9-12 (CANCELLED).

CLAIM 13(CURRENTLY AMENDED). A method of securing a polishing pad to a platen of a CMP apparatus, the polishing pad having a working-surface section and a nonworking-surface section, the polishing pad comprising a first portion of a hook-and-pile fastening means attached to the nonworking-surface section, and the platen comprising a pad-supporting surface having a second, mating portion of the hook-and-pile fastening means, said method comprising:

(a) removably attaching the nonworking-surface section of the polishing pad to the pad-supporting surface of the platen with hook-and-pile fastening means having a shear strength in the range of 50-250 kPa, and peel strength in the range of 0.2-0.6 N/m.;

(b) said step (a) of removably attaching comprising attaching the first portion of the hook-and-pile fastening means to the second portion of the hook-and-pile fastening means.

CLAIM 14(CURRENTLY AMENDED). The method of securing a polishing pad to a platen of a CMP apparatus according to claim 13, further comprising:

(c) after said step (a) of removably attaching, removing the polishing pad from the platen when the polishing pad has become worn;

(d) said step ~~(e)~~ of removing the polishing pad comprising peeling the first portion of the hook-and-pile fastening means from the second portion of the hook-and-pile fastening means.

CLAIM 15(CURRENTLY AMENDED). The method of securing a polishing pad to a platen of a CMP apparatus according to claim 14, further comprising;

(e) removably attaching the nonworking-surface section of another, new said polishing pad to the pad-supporting surface of the platen ~~of said step (a)~~ ;

(f) said step ~~(e)~~ of removably attaching the nonworking-surface section of another, new said polishing pad comprising attaching the first portion of the hook-and-pile fastening means of the nonworking-surface section thereof to said second portion of the hook-and-pile fastening means used in said step ~~(b)~~ of attaching the first portion of the hook-and-pile fastening means to the second portion of the hook-and-pile fastening means.